ASSOCIATION CONNECTION ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and M	fg Informa	tion		
upplier Inforn															
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
onsemi												2023-06-08			
Contact Name			Title - Contact			1	Phone - Contact*					Email - Contact*			
Product-Env-Stew	ards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
uthorized Repres	entative*		Title - Representative]	Phone - Representative*				Email - Representative*				
Product-Env-Stew	ards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Request	Requester Item Number Mfr Item		em Number Mfr Item Name				Effective Date		ring Site	Weight*		UOM	Unit Type		
		NB100LV	/EP222MNG	BBG ECL PECL	CLOCK DRV	'R	2023-06-08			PH1		2	23.89	mg	Each
Ianufacturing	Process Information	on													
Terminal Plating / Grid Array Material		rial Te	Terminal Base Alloy J-STD-020 M		SL Rating	Peak Process Body Ten		ody Temperat	erature Max Time at Peak T		Temperat	ure Num	ber of Reflow Cyc	eles	
Matte Ti	n (Sn) - annealed	Cl	U Alloy	2	2		260		C	30		secon	ds 3		
omments															
TTENTION: MS	L 2 Rated item requires I	Ory Pack (af	fter electrical	test)											
or more informati	on regarding material co	mposition p	olease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	led						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the						
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.24	mg	Supplier	Silicon (Si)	7440-21-3		0.24	mg
Die Attach	0.6	mg	Supplier	Silver (Ag)	7440-22-4		0.45	mg
			Supplier	Epoxy resins	129915-35-1		0.15	mg
Lead Frame	9.44	mg	Supplier	Silver (Ag)	7440-22-4		1.6048	mg
			Supplier	Iron (Fe)	7439-89-6		0.0755	mg
			Supplier	Copper (Cu)	7440-50-8		7.7597	mg
Mold Compound-Black	11.38	mg		Epoxy resin	proprietary data		0.7966	mg
			Supplier	Phenolic Resin	Proprietary Data		0.7966	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.707	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0569	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		8.0229	mg
Plating	0.67	mg	Supplier	Tin (Sn)	7440-31-5		0.67	mg
Wire Bond - Au	1.56	mg	Supplier	Gold (Au)	7440-57-5		1.56	mg